

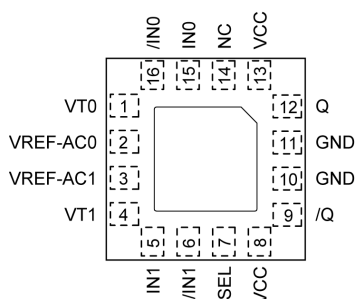
Ordering Information⁽¹⁾

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY58611UMG	QFN-16	Industrial	611U with Pb-Free bar-line indicator	NiPdAu Pb-Free
SY58611UMGTR ⁽²⁾	QFN-16	Industrial	611U with Pb-Free bar-line indicator	NiPdAu Pb-Free

Notes:

1. Contact factory for die availability. Dice are guaranteed at $T_A = 25^\circ\text{C}$, DC Electricals only.
2. Tape and Reel.

Pin Configuration



16-Pin QFN

Truth Table

SEL	Output
0	IN0 Selected
1	IN1 Selected

Pin Description

Pin Number	Pin Name	Pin Function
1, 4	VT0, VT1	Input Termination Center-Tap: Each side of the differential input pair terminates to the VT pin. This pin provides a center-tap to a termination network for maximum interface flexibility. See "Input Interface Applications" subsection.
2, 3	VREF-AC0, VREF-AC1	Reference Voltage: These outputs bias to $V_{CC}-1.2\text{V}$. They are used for AC-coupling inputs IN and /IN. Connect VREF-AC directly to the corresponding VT pin. Bypass with $0.01\mu\text{F}$ low ESR capacitor to VCC. Due to limited drive capability, the VREF-AC pin is only intended to drive its respective VT pin. Maximum sink/source current is $\pm 0.5\text{mA}$. See "Input Interface Applications" subsection.
5, 6 15, 16	IN1, /IN1 IN0, /IN0	Differential Inputs: These input pairs are the differential signal inputs to the device. Inputs accept AC- or DC-Coupled differential signals as small as 100mV (200mV_{PP}). Each pin of the pairs internally terminates with 50Ω to the V_T pin. If the input swing falls below a certain threshold (typical 30mV), the Fail Safe Input (FSI) feature will guarantee a stable output by latching the output to its last valid state. See "Input Interface Applications" subsection.
7	SEL	Single-Ended Input: This single-ended TTL/CMOS-compatible input selects the inputs to the multiplexer. Note that this input is internally connected to a $25\text{k}\Omega$ pull-up resistor and will default to logic HIGH state if left open. The input-switching threshold is $V_{CC}/2$.
8, 13	VCC	Positive Power Supply: Bypass with $0.1\mu\text{F}/0.01\mu\text{F}$ low ESR capacitors as close to the V_{CC} pins as possible.
9, 12	/Q, Q	LVDS Differential Output Pair: Differential buffered output copy of the selected input signal. The output swing is typically 325mV . Normally terminated 100_Ω across the output (Q and /Q). See "LVDS Output Interface Applications" subsection.
10, 11	GND, Exposed pad	Ground. Exposed pad must be connected to a ground plane that is the same potential as the ground pin.
14	NC	No connect.

Absolute Maximum Ratings⁽¹⁾

Supply Voltage (V_{CC}) $-0.5V$ to $+4.0V$
 Input Voltage (V_{IN}) $-0.5V$ to V_{CC}
 LVDS Output Current (I_{OUT}) $\pm 10mA$
 Input Current
 Source or Sink Current on (I_N , $/I_N$) $\pm 50mA$
 Current (V_{REF})
 Source or sink current on V_{REF-AC} ⁽⁴⁾ $\pm 0.5mA$
 Maximum operating Junction Temperature $125^{\circ}C$
 Lead Temperature (soldering, 20sec.) $260^{\circ}C$
 Storage Temperature (T_s) $-65^{\circ}C$ to $+150^{\circ}C$

Operating Ratings⁽²⁾

Supply Voltage (V_{CC}) $+2.375V$ to $+2.635V$
 Ambient Temperature (T_A) $-40^{\circ}C$ to $+85^{\circ}C$
 Package Thermal Resistance⁽³⁾
 QFN
 Still-air (θ_{JA}) $60^{\circ}C/W$
 Junction-to-Board (ψ_{JB}) $33^{\circ}C/W$

DC Electrical Characteristics⁽⁵⁾

$T_A = -40^{\circ}C$ to $+85^{\circ}C$ unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{CC}	Power Supply Voltage Range		2.375	2.5	2.625	V
I_{CC}	Power Supply Current	No load, max. V_{CC}		40	60	mA
R_{IN}	Input Resistance (I_N -to- V_T , $/I_N$ -to- V_T)		45	50	55	Ω
R_{DIFF_IN}	Differential Input Resistance (I_N -to- $/I_N$)		90	100	110	Ω
V_{IH}	Input HIGH Voltage (I_N , $/I_N$)		1.2		V_{CC}	V
V_{IL}	Input LOW Voltage (I_N , $/I_N$)		0.2		$V_{IH}-0.1$	V
V_{IN}	Input Voltage Swing (I_N , $/I_N$)	see Figure 3a, Note 6	0.1		1.0	V
V_{DIFF_IN}	Differential Input Voltage Swing ($ I_N - /I_N $)	see Figure 3b	0.2			V
V_{IN_FSI}	Input Voltage Threshold that Triggers FSI			30	100	mV
V_{REF-AC}	AC Reference Voltage	$I_{VREF-AC} = \pm 0.5mA$	$V_{CC}-1.3$		$V_{CC}-1.0$	V
V_{T_IN}	Voltage from Input to V_T				1.28	V

Notes:

1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the device's most negative potential on the PCB. ψ_{JB} and θ_{JA} values are determined for a 4-layer board in still-air number, unless otherwise stated.
4. Due to the limited drive capability, use for input of the same package only.
5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
6. V_{IN} (max) is specified when V_T is floating.

LVDS Output DC Electrical Characteristics⁽⁷⁾

$V_{CC} = +2.5V \pm 5\%$, $R_L = 100\Omega$ across the output pair; $T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{OUT}	Output Voltage Swing (Q, /Q)	See Figure 3a	250	325		mV
V_{DIFF_OUT}	Differential Output Voltage Swing Q-/Q	See Figure 3b	500	650		mV
V_{OCM}	Output Common Mode Voltage (Q, /Q)	See Figure 5b	1.125	1.20	1.275	V
ΔV_{OCM}	Change in Common Mode Voltage (Q, /Q)	See Figure 5b	-50		50	mV

LVTTTL/CMOS DC Electrical Characteristics⁽⁷⁾

$V_{CC} = 2.5V \pm 5\%$; $T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
V_{IH}	Input HIGH Voltage		2.0			V
V_{IL}	Input LOW Voltage				0.8	V
I_{IH}	Input HIGH Current		-125		30	μA
I_{IL}	Input LOW Current		-300			μA

Notes:

7. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

AC Electrical Characteristics⁽⁸⁾

$V_{CC} = +2.5V \pm 5\%$, $R_L = 100\Omega$ across the output pair; Input $t_r/t_f \leq 300ps$, $T_A = -40^\circ C$ to $+85^\circ C$, unless otherwise stated.

Symbol	Parameter	Condition	Min	Typ	Max	Units
f_{MAX}	Maximum Frequency	NRZ Data	3.2			Gbps
		$V_{OUT} > 200mV$ Clock	2.5	3		GHz
t_{PD}	Propagation Delay IN-to-Q	$V_{IN}: 100mV-200mV$	190	330	470	ps
		$V_{IN}: > 200mV$	150	280	420	ps
	SEL-to-Q		150		450	ps
t_{Skew}	Input-to-Input Skew	Note 9, 10		5	20	ps
	Part-to-Part Skew	Note 11			150	ps
t_{Jitter}	Data Random Jitter	Note 12			1	ps _{RMS}
	Deterministic Jitter	Note 13			10	ps _{PP}
	Clock Cycle-to-Cycle Jitter	Note 14			1	ps _{RMS}
	Total Jitter	Note 15			10	ps _{PP}
t_r, t_f	Output Rise/Fall Times (20% to 80%)	At full output swing.	40	80	120	ps
	Duty Cycle	Differential I/O	47		53	%

Notes:

8. High-frequency AC-parameters are guaranteed by design and characterization.
9. Input-to-Input skew is the time difference between the two inputs and one output, under identical input transitions.
10. Input-to-Input Skew is included in IN-to-Q propagation delay.
11. Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature, same transition edge, and no skew at the edges at the respective inputs.
12. Random jitter is measured with a K28.7 pattern, measured at $\leq f_{MAX}$.
13. Deterministic jitter is measured at 2.5Gbps with both K28.5 and $2^{23}-1$ PRBS pattern.
14. Cycle-to-cycle jitter definition: the variation period between adjacent cycles over a random sample of adjacent cycle pairs. $t_{JITTER_CC} = T_n - T_{n+1}$, where T is the time between rising edges of the output signal.
15. Total jitter definition: with an ideal clock input frequency of $\leq f_{MAX}$ (device), no more than one output edge in 10^{12} output edges will deviate by more than the specified peak-to-peak jitter value.

Functional Description

Fail-Safe Input (FSI)

The input includes a special fail-safe circuit to sense the amplitude of the input signal and to latch the output when there is no input signal present, or when the amplitude of the input signal drops sufficiently below 100mV_{PK} (200mV_{PP}), typically 30mV_{PK} . Refer to Figure 1b.

Input Clock Failure Case

If the input clock fails to a floating, static, or extremely low signal swing such that the voltage swing across the input pair is significantly less than 100mV , FSI

function will eliminate a metastable condition and latch the output to the last valid state. No ringing and no undetermined state will occur at the output under these conditions. The output recovers to normal operation once the input signal returns to a valid state with a typical swing greater than 30mV .

Note that the FSI function will not prevent duty cycle distortion in case of a slowly deteriorating (but still toggling) input signal. Due to the FSI function, the propagation delay will depend on rise and fall time of the input signal and on its amplitude. Refer to "Typical Operating Characteristics" for detailed information.

Timing Diagrams

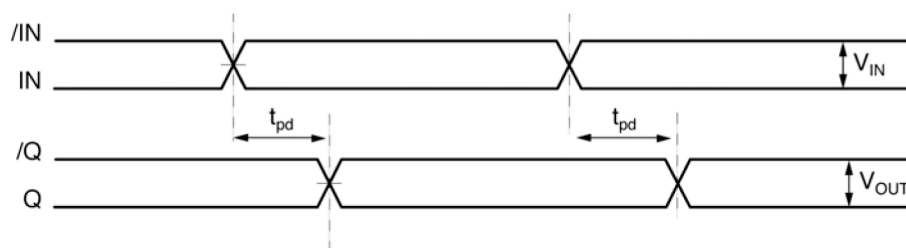


Figure 1a. Propagation Delay

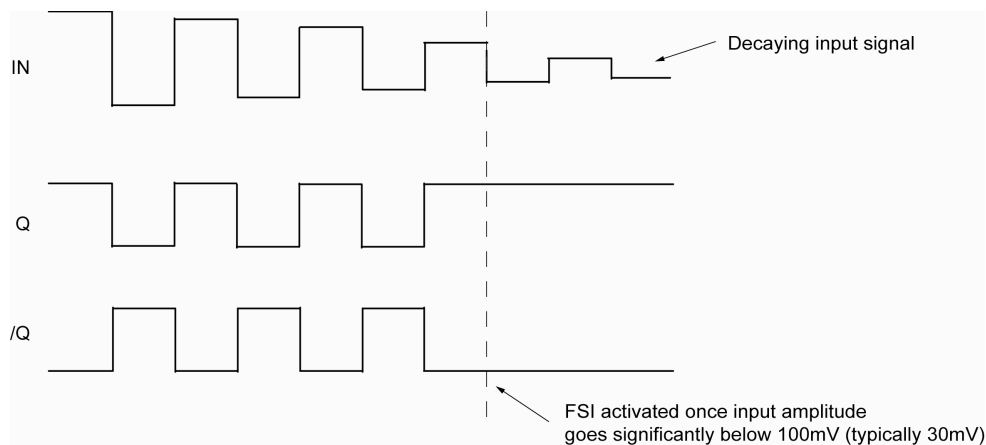


Figure 1b. Fail-Safe Feature

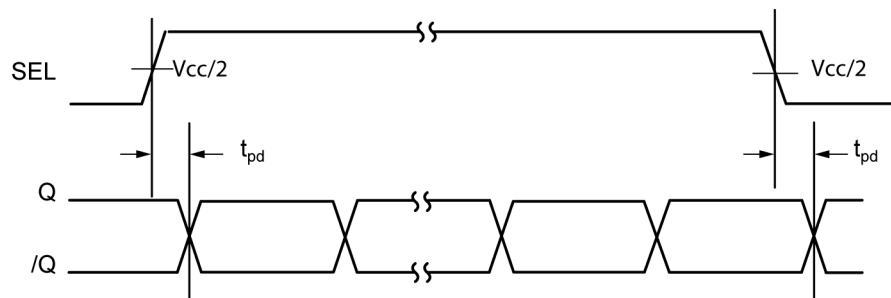


Figure 1c. SEL-to-Q Delay

Input Stage

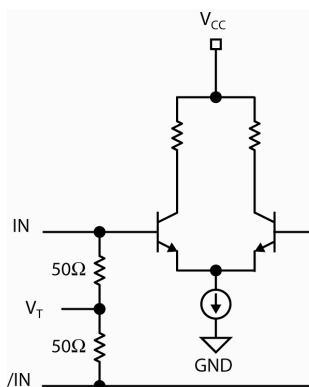


Figure 2. Simplified Differential Input Buffer

Single-Ended and Differential Swings

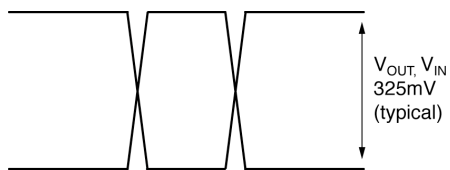


Figure 3a. Single-Ended Swing

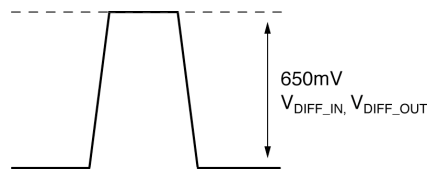
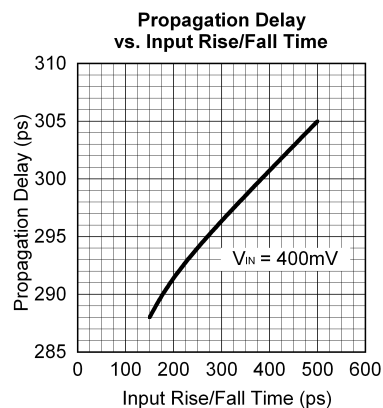
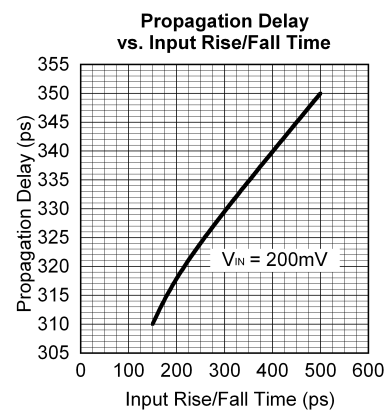
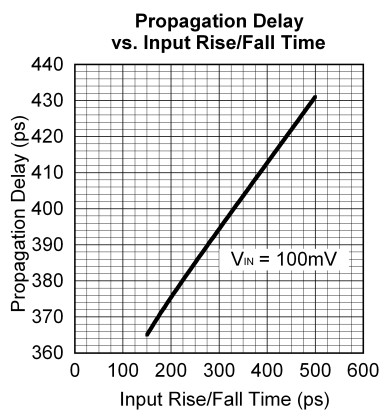
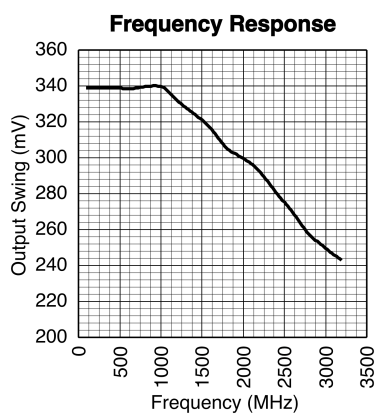


Figure 3b. Differential Swing

Typical Characteristics

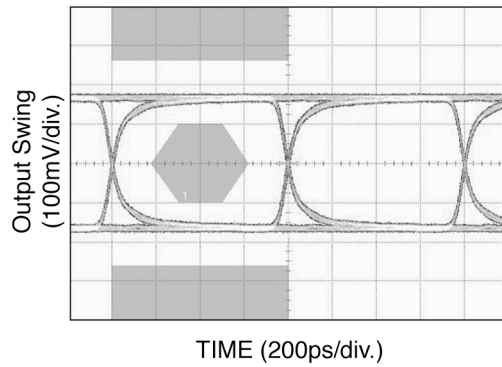
$V_{CC} = 2.5V$, $GND = 0V$, $V_{IN} = 100mV$, $R_L = 100\Omega$ across the output pair, $T_A = 25^\circ C$, unless otherwise stated.



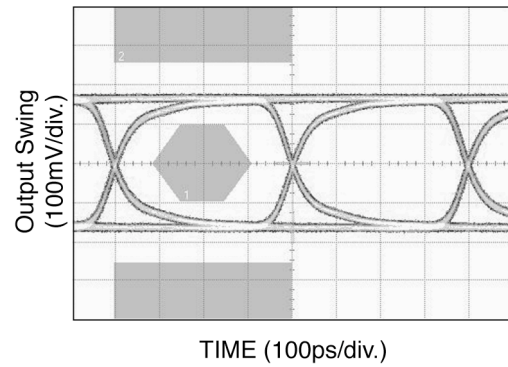
Functional Characteristics

$V_{CC} = 2.5V$, $GND = 0V$, $V_{IN} = 325mV$, $R_L = 100\Omega$ across the output pair, $T_A = 25^\circ C$, unless otherwise stated.

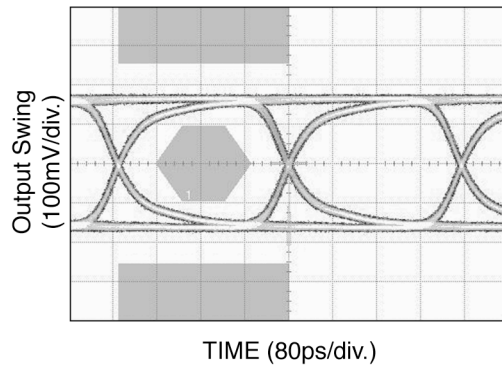
1.25Gbps Data



2.5Gbps Data

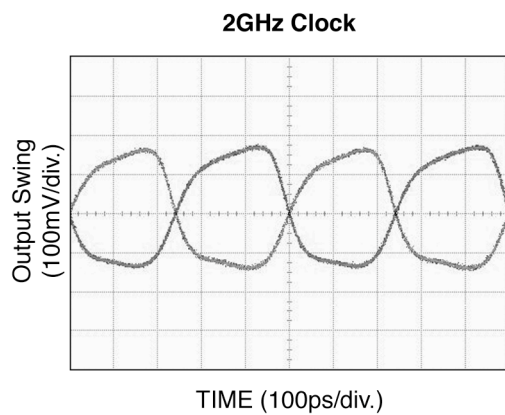
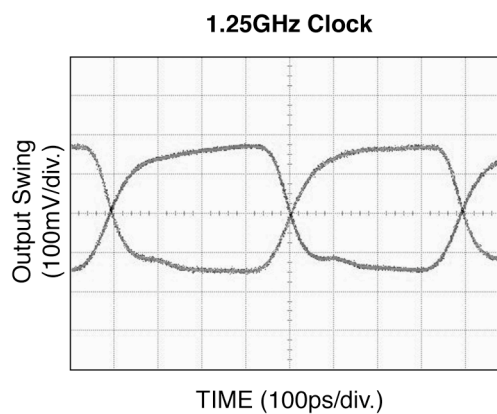
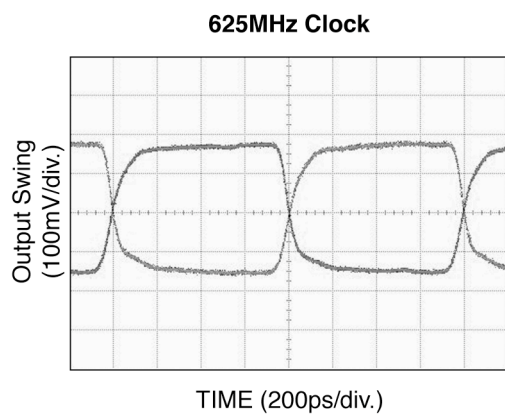


3.2Gbps Data

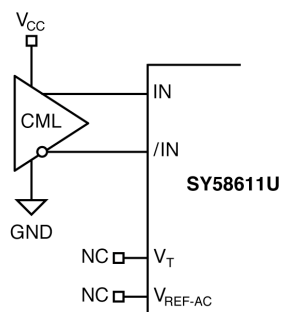


Functional Characteristics (continued)

$V_{CC} = 2.5V$, $GND = 0V$, $V_{IN} = 325mV$, $R_L = 100\Omega$ across the output pair, $T_A = 25^\circ C$, unless otherwise stated.

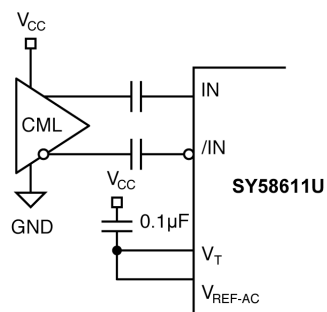


Input Interface Applications

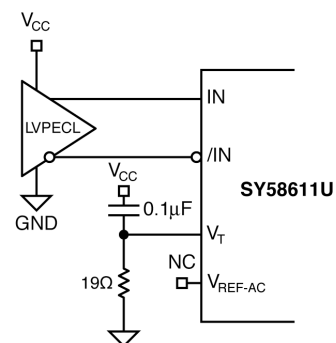


**Figure 4a. CML Interface
(DC-Coupled)**

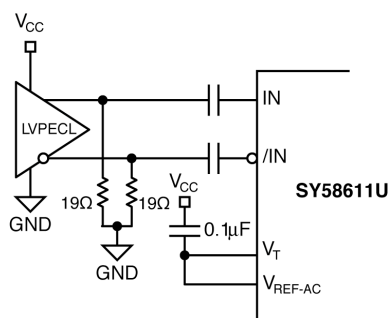
Option: May connect V_T to V_{CC}



**Figure 4b. CML Interface
(AC-Coupled)**



**Figure 4c. LVPECL Interface
(DC-Coupled)**



**Figure 4d. LVPECL Interface
(AC-Coupled)**

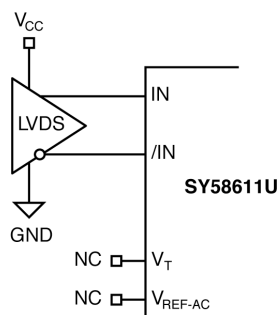


Figure 4e. LVDS Interface

LVDS Output Interface Applications

LVDS specifies a small swing of 325mV typical, on a nominal 1.2V common mode above ground. The common mode voltage has tight limits to permit large variations in the ground between and LVDS driver and receiver. Also, change in common mode voltage, as a function of data input, is kept to a minimum, to keep EMI low.

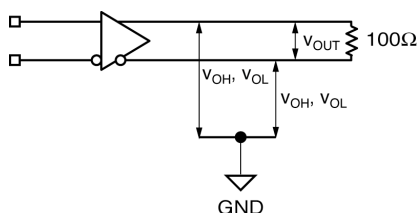


Figure 5a. LVDS Differential Measurement

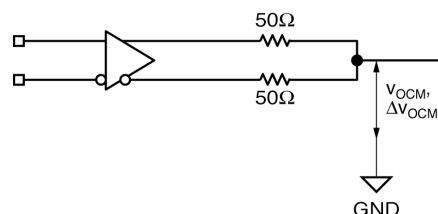
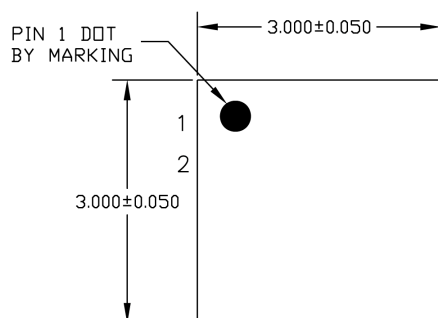


Figure 5b. LVDS Common Mode Measurement

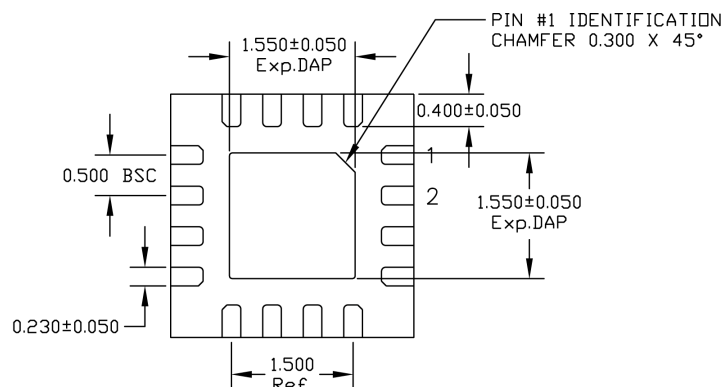
Related Products and Support Documentation

Part Number	Function	Data Sheet Link
SY58609U	4.25Gbps Precision, CML 2:1 MUX with Internal Termination and Fail Safe Input	http://www.micrel.com/_PDF/HBW/sy58609u.pdf
SY58610U	3.2Gbps Precision, LVPECL 2:1 MUX with Internal Termination and Fail Safe Input	http://www.micrel.com/_PDF/HBW/sy58610u.pdf
HBW Solutions	New Products and Termination Application Notes	http://www.micrel.com/page.do?page=/product-info/as/HBWolutions.shtml

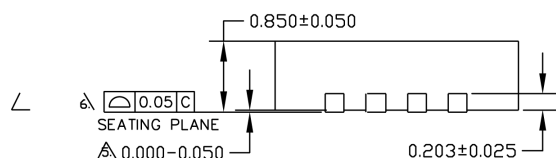
Package Information



TOP VIEW



BOTTOM VIEW



SIDE VIEW

NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
 2. MAX. PACKAGE WARPAGE IS 0.05 mm.
 3. MAXIMUM ALLOWABLE BURRS IS 0.076 mm IN ALL DIRECTIONS.
 4. PIN #1 ID ON TOP WILL BE LASER/INK MARKED.
- △ APPLIED ONLY FOR TERMINALS.
△ APPLIED FOR EXPOSED PAD AND TERMINALS.

16-Pin (3mm x 3mm) QFN

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